

IN THE CLAIMS:

Revise the claims as follows:

1. (Currently Amended) A method of manufacturing an electronic part in which at least one circuit element is formed on a surface of a ceramic substrate and conductive balls are used as terminals of the electronic part, comprising:

a first step of forming at least one circuit element on the surface of a large ceramic substrate including division grooves longitudinally and laterally provided on the surface thereof;

a second step of fixing the conductive balls to terminal portions of the circuit element; and

a third step of applying stress to the large ceramic substrate to open the division grooves, to divide the substrate, the first, second, and third steps being performed in the stated order,

~~wherein the stress to be applied in the third step is substantially equally applied to a large number of conductive balls, or the stress is applied to the substrate and/or the circuit element, or a part of the stress is substantially equally applied to a large number of conductive balls and a remainder of the stress is applied to the substrate and/or the circuit element~~

wherein the third step is performed in a state in which a buffer member is located on the surface of the large ceramic substrate to which the conductive balls are fixed, the buffer member having a concave portion to house the conductive balls and a convex portion in contact with the surface of the substrate and/or the circuit element and by doing so, all stress to be applied in the third step is applied to the substrate and/or the circuit element.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) A method of manufacturing an electronic part according to claim 1 , wherein the division grooves exist on the surface of the substrate to which the conductive balls are fixed.

5. (Cancelled)

6. (Previously Presented) A method of manufacturing an electronic part according to claim 1, wherein the conductive balls are fixed to the substrate using a conductive bonding agent.

7. (Currently Amended) A method of manufacturing an electronic part in which at least one circuit element is formed on a surface of a ceramic substrate and conductive balls are used as terminals of the electronic part, comprising:

a first step of forming at least one circuit element on the surface of a large ceramic substrate;

a second step of fixing the conductive balls to terminal portions of the circuit element;

a third step of forming division grooves for the large ceramic substrate on the surface of the substrate on which the circuit element exists; and

a fourth step of applying stress to the large ceramic substrate to open the division grooves, to divide the substrate, the first, second, third and fourth steps being performed in the stated order,

~~wherein the stress to be applied in the fourth step is substantially equally applied to a large number of conductive balls, or the stress is applied to the substrate and/or the circuit element, or a part of the stress is substantially equally applied to a large number of conductive balls and a remainder of the stress is applied to the substrate and/or the circuit element~~

wherein the fourth step is performed in a state in which a buffer member is located on the surface of the large ceramic substrate to which the conductive balls are fixed, the buffer member having a concave portion to house the conductive balls and a convex portion in contact with the surface of the substrate and/or the circuit element and by doing so, all stress to be applied in the fourth step is applied to the substrate and/or the circuit element.

8. (Cancelled)

9. (Currently Amended) A method of manufacturing an electronic part according to claim 7, wherein the division grooves exist on the surface of the substrate to which the conductive balls are fixed.

10. (Previously Presented) A method of manufacturing an electronic part according to claim 7, wherein the conductive balls are fixed to the substrate using a conductive bonding agent.

11. (Previously Presented) A method of manufacturing an electronic part according to claim 1, wherein the division grooves exist on the surface of the substrate on which the circuit element is formed.

12. (New) A method of manufacturing an electronic part according to claim 1, wherein the concave portion of the buffer member does not come into contact with the conductive balls.

13. (New) A method of manufacturing an electronic part according to claim 7, wherein the concave portion of the buffer member does not come into contact with the conductive balls.